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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE: NEW ASSIGNMENT NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YUJI KAIMASU	11/11/2015
JUNGO MATSUI	11/11/2015

RECEIVING PARTY DATA

Name:	YASUNAGA CORPORATION	
Street Address:	3860 MIDORIGAOKA NAKA-MACHI	
Internal Address:	IGA-SHI	
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State/Country:	JAPAN	
Postal Code:	5180834	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14784695

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 57831-5009 MARY JANE BOSWELL NAME OF SUBMITTER: SIGNATURE: /Mary Jane Boswell/ **DATE SIGNED:** 01/12/2016

Total Attachments: 1

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PATENT REEL: 037463 FRAME: 0366 503644674

ASSIGNMENT

WHEREAS WE, the below named inventors, (hereinafter referred to as "Assignors"), have made an invention entitled: METHOD OF FORMING FRACTURE START PORTION OF CON ROD AND FORMING DEVICE

for which WE filed an application for United States Letters Patent on October 15, 2015, (Application No 14/784,695); and

WHEREAS YASUNAGA CORPORATION whose post office address is 3860 Midorigaoka Naka-machi, Iga-shi, Mie 5180834 Japan (hereinafter referred to as "Assignee"), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Director of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, WE have hereunto set my hands.

Full Name of first Assignor	Yuji KAIMASU
Address	c/o YASUNAGA CORPORATION, 3860 Midorigaoka Naka-machi, Iga-shi, Mie 5180834 Japan
Signature	貝增祐士
Date	11th November 2015
Full Name of second Assignor	Jungo MATSUI
Address	c/o YASUNAGA CORPORATION, 3860 Midorigaoka Naka-machi, Iga-shi, Mie 5180834 Japan
Signature	松井 淳悟

Morgan, Lewis & Bocklus LLP

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RECORDED: 01/12/2016

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